

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT																
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT																
<b>CONVEYING PARTY DATA</b>																	
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Toshihiko TSUKATANI</td> <td>10/21/2008</td> </tr> <tr> <td>Takao MAEDA</td> <td>10/21/2008</td> </tr> <tr> <td>Junichi NAKAYAMA</td> <td>10/21/2008</td> </tr> <tr> <td>Hirofumi KAWAZOE</td> <td>10/21/2008</td> </tr> <tr> <td>Masaru KONYA</td> <td>10/21/2008</td> </tr> <tr> <td>Noriaki HAMAYA</td> <td>10/21/2008</td> </tr> <tr> <td>Hajime NAKANO</td> <td>10/21/2008</td> </tr> </tbody> </table>		Name	Execution Date	Toshihiko TSUKATANI	10/21/2008	Takao MAEDA	10/21/2008	Junichi NAKAYAMA	10/21/2008	Hirofumi KAWAZOE	10/21/2008	Masaru KONYA	10/21/2008	Noriaki HAMAYA	10/21/2008	Hajime NAKANO	10/21/2008
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<b>RECEIVING PARTY DATA</b>																	
<b>Name:</b>	Shin-Etsu Chemical Co., Ltd.																
<b>Street Address:</b>	6-1, Otemachi 2-chome, Chiyoda-ku,																
<b>City:</b>	Tokyo																
<b>State/Country:</b>	JAPAN																
<b>PROPERTY NUMBERS Total: 1</b>																	
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12258850</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12258850												
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<b>CORRESPONDENCE DATA</b>																	
<b>Fax Number:</b>	(202)822-1111																
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>																	
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<b>Correspondent Name:</b>	Westerman, Hattori, Daniels & Adrian LLP																
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<b>Address Line 4:</b>	Washington,, DISTRICT OF COLUMBIA 20036																
<b>ATTORNEY DOCKET NUMBER:</b>	082436																

OP \$40.00 12258850

NAME OF SUBMITTER:

Scott M. Daniels

Total Attachments: 2

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# U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by

(Insert ASSIGNEE's Name(s) Address(es))

Shin-Etsu Chemical Co., Ltd. of  
6-1, Otemachi 2-chome, Chiyoda-ku, Tokyo, Japan

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

(Title of Invention)

Wafer

(\*If the assignment is being filed after the filing of the application, this section must be completed)

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

\* filed on \_\_\_\_\_ Serial No. \_\_\_\_\_

(Westerman, Hattori, Daniels & Adrian, LLP is hereby authorized to insert the series code, serial number and/or filing date hereon, when known)

and all Letters Patent of the United States to be obtained therefore on said application or any continuation, divisional, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with the application and any continuation, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, divisional, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

<u>Toshihiko Tsukatani</u> (Signature)	<u>Toshihiko TSUKATANI</u> (Type Name)	<u>October 21, 2008</u> (Date)
<u>Takao Maeda</u> (Signature)	<u>Takao MAEDA</u> (Type Name)	<u>October 21, 2008</u> (Date)
<u>Junichi Nakayama</u> (Signature)	<u>Junichi NAKAYAMA</u> (Type Name)	<u>October 21, 2008</u> (Date)
<u>Hirofumi Kawazoe</u> (Signature)	<u>Hirofumi KAWAZOE</u> (Type Name)	<u>October 21, 2008</u> (Date)
<u>Masaru Konya</u> (Signature)	<u>Masaru KONYA</u> (Type Name)	<u>October 21, 2008</u> (Date)
<u>Noriaki Hamaya</u> (Signature)	<u>Noriaki HAMAYA</u> (Type Name)	<u>October 21, 2008</u> (Date)

NO LEGALIZATION REQUIRED

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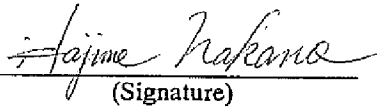
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(Signatures)

	Hajime NAKANO	October 21, 2008
_____ (Signature)	_____ (Type Name)	_____ (Date)
_____ (Signature)	_____ (Type Name)	_____ (Date)
_____ (Signature)	_____ (Type Name)	_____ (Date)
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